

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/01/2022

Details for "LM5158RTER"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LM5158RTER	NIPDAU	Level-2-260C-1 YEAR	TI Semiconductor	RTE 16	3x3x0.75	27.2

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.11896	99.997478	999975	0.437643	4376
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000841	8	0.000004	0
Precious Metals	Silver	7440-22-4	0.000002	0.001681	17	0.000007	0
Sub-Total			0.118963	100	1000000	0.437654	4377
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.410589	80.000039	800000	1.510518	15105
Thermoplastics	Epoxy	85954-11-6	0.102647	19.999961	200000	0.377629	3776
Sub-Total			0.513236	100	1000000	1.888147	18881
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	15.89576	97.52	975200	58.479009	584790
Copper and Its Alloys	Iron	7439-89-6	0.3749	2.3	23000	1.379222	13792
Copper and Its Alloys	Phosphorus	7723-14-0	0.00489	0.03	300	0.01799	180
Zinc and Its Alloys	Zinc	7440-66-6	0.02445	0.15	1500	0.089949	899
Sub-Total			16.3	100	1000000	59.96617	599662
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.4756	95.12	951200	1.749688	17497
Precious Metals	Gold	7440-57-5	0.0039	0.78	7800	0.014348	143
Precious Metals	Palladium	7440-05-3	0.0205	4.1	41000	0.075418	754
Sub-Total			0.5	100	1000000	1.839453	18395
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	7.580526	88.000001	880000	27.888043	278880
Other Organic Materials	Chlorine	7782-50-5	0.000086	0.000998	10	0.000316	3
Other Plastics and Rubber	Carbon Black	1333-86-4	0.025843	0.300003	3000	0.095074	951
Thermoplastics	Epoxy	85954-11-6	1.007779	11.698997	116990	3.707524	37075
Sub-Total			8.614234	100	1000000	31.690958	316910
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.13556	100	1000000	4.177619	41776
Sub-Total			1.13556	100	1000000	4.177619	41776
Total			27.181993			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.